

# MODEL TEAM-100

Automatic Wafer Protective Tape Lamination System

## Outline

The ideal system for laminating tape within the circumference of the wafer prior to the backgrind process.

## Features

- Vacuum chamber application eliminates air bubbles and preserves integrity of wafers.
- Normal B/G tape roll applicable. Pre-cut tape is not necessary.
- Ability to determine the diameter of the cut and laminate within the circumference of the wafer.
- Reduced tension on the lamination tape.



Patent Pending

Specification		TEAM-100
Throughput		50 wafers/hour ( Depend on data setting )
Wafer Size		5 inch、 6 inch、 8 inch
Tape Width		8 inch : W 150mm、 6 inch : W 180mm、 8 inch : W 230mm
Utilities	Power	AC100V Single phase 50 / 60Hz 2.0 KVA
	Air	Pressure 0.5Mpa 100NI/min
	Vacuum source	74Kpa
Dimensions		D 1,000 × W 1,400 × H 1,650 mm
Weight		600 kg

System appearance and specifications are subject to change without prior notice from the supplier.

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